

# IRL1004PBF Datasheet

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DiGi Electronics Part Number	IRL1004PBF-DG
Manufacturer	<a href="#">Infineon Technologies</a>
Manufacturer Product Number	IRL1004PBF
Description	MOSFET N-CH 40V 130A TO220AB
Detailed Description	N-Channel 40 V 130A (Tc) 200W (Tc) Through Hole TO-220AB



Tel: +00 852-30501935

RFQ Email: [Info@DiGi-Electronics.com](mailto:Info@DiGi-Electronics.com)

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## Purchase and inquiry

Manufacturer Product Number:

IRL1004PBF

Series:

HEXFET®

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

40 V

Drive Voltage (Max Rds On, Min Rds On):

4.5V, 10V

Vgs(th) (Max) @ Id:

1V @ 250µA

Vgs (Max):

±16V

FET Feature:

-

Operating Temperature:

-55°C ~ 175°C (Tj)

Supplier Device Package:

TO-220AB

Base Product Number:

IRL1004

Manufacturer:

Infineon Technologies

Product Status:

Active

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

130A (Tc)

Rds On (Max) @ Id, Vgs:

6.5mOhm @ 78A, 10V

Gate Charge (Qg) (Max) @ Vgs:

100 nC @ 4.5 V

Input Capacitance (Ciss) (Max) @ Vds:

5330 pF @ 25 V

Power Dissipation (Max):

200W (Tc)

Mounting Type:

Through Hole

Package / Case:

TO-220-3

## Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99



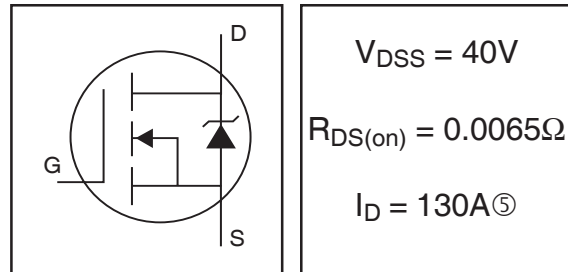
International  
**IR** Rectifier

PD - 95403

# IRL1004PbF

## HEXFET® Power MOSFET

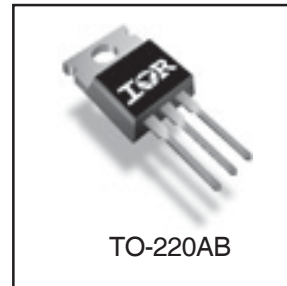
- Logic-Level Gate Drive
- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Lead-Free



### Description

Fifth Generation HEXFET® power MOSFETs from International Rectifier utilize advanced processing techniques to achieve the lowest possible on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



### Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	130 <sup>Ⓢ</sup>	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	92 <sup>Ⓢ</sup>	
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	520	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation	200	W
	Linear Derating Factor	1.3	W/°C
$V_{GS}$	Gate-to-Source Voltage	± 16	V
$E_{AS}$	Single Pulse Avalanche Energy <sup>②</sup>	700	mJ
$I_{AR}$	Avalanche Current <sup>③</sup>	78	A
$E_{AR}$	Repetitive Avalanche Energy <sup>④</sup>	20	mJ
dv/dt	Peak Diode Recovery dv/dt <sup>⑤</sup>	5.0	V/ns
$T_J$	Operating Junction and	-55 to + 175	°C
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds		
	Mounting torque, 6-32 or M3 srew	10 lbf•in (1.1N•m)	

### Thermal Resistance

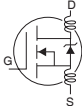
	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	0.75	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.50	—	
$R_{\theta JA}$	Junction-to-Ambient	—	62	

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International  
IR RectifierElectrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	40	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.04	—	V/°C	Reference to $25^\circ\text{C}$ , $I_D = 1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.0065	$\Omega$	$V_{GS} = 10V, I_D = 78A$ ④
		—	—	0.009		$V_{GS} = 4.5V, I_D = 65A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	1.0	—	—	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
$g_{fs}$	Forward Transconductance	63	—	—	S	$V_{DS} = 25V, I_D = 78A$
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	25	$\mu\text{A}$	$V_{DS} = 40V, V_{GS} = 0V$
		—	—	250		$V_{DS} = 32V, V_{GS} = 0V, T_J = 150^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 16V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -16V$
$Q_g$	Total Gate Charge	—	—	100	nC	$I_D = 78A$
$Q_{gs}$	Gate-to-Source Charge	—	—	32		$V_{DS} = 32V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge	—	—	43		$V_{GS} = 4.5V$ , See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	16	—	ns	$V_{DD} = 20V$
$t_r$	Rise Time	—	210	—		$I_D = 78A$
$t_{d(off)}$	Turn-Off Delay Time	—	25	—		$R_G = 2.5\Omega, V_{GS} = 4.5V$
$t_f$	Fall Time	—	14	—		$R_D = 0.18\Omega$ , See Fig. 10 ④
$L_D$	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.) from package and center of die contact
$L_S$	Internal Source Inductance	—	7.5	—		
$C_{iss}$	Input Capacitance	—	5330	—	pF	$V_{GS} = 0V$
$C_{oss}$	Output Capacitance	—	1480	—		$V_{DS} = 25V$
$C_{rss}$	Reverse Transfer Capacitance	—	320	—		$f = 1.0\text{MHz}$ , See Fig. 5

## Source-Drain Ratings and Characteristics

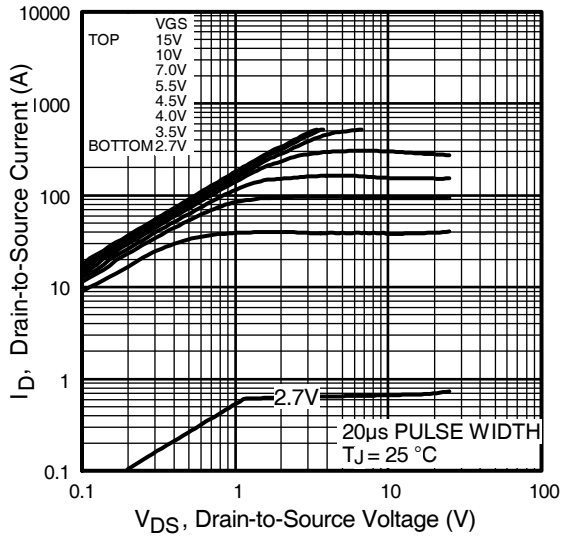
	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	130	A	MOSFET symbol showing the integral reverse p-n junction diode.
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	520		
$V_{SD}$	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}, I_S = 78A, V_{GS} = 0V$ ④
$t_{rr}$	Reverse Recovery Time	—	78	120	ns	$T_J = 25^\circ\text{C}, I_F = 78A$
$Q_{rr}$	Reverse Recovery Charge	—	180	270	nC	$di/dt = 100A/\mu\text{s}$ ④
$t_{on}$	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S+L_D$ )				

## Notes:

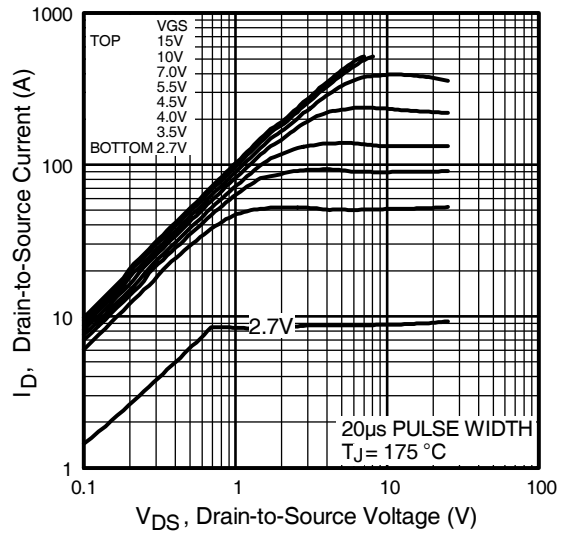
- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.23\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = 78A$ . (See Figure 12)
- ③  $I_{SD} \leq 78A$ ,  $di/dt \leq 370A/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  
 $T_J \leq 175^\circ\text{C}$

④ Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ 

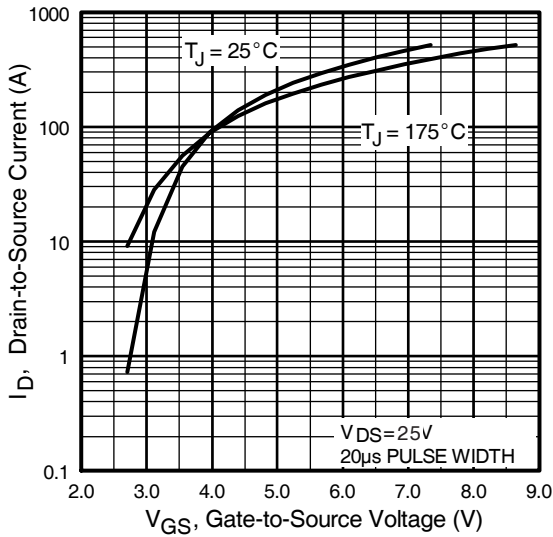
⑤ Calculated continuous current based on maximum allowable junction temperature; for recommended current-handling of the package refer to Design Tip #93-4



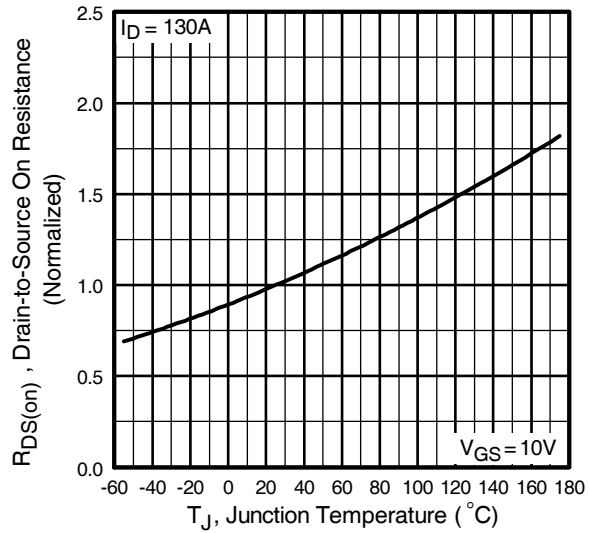
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics

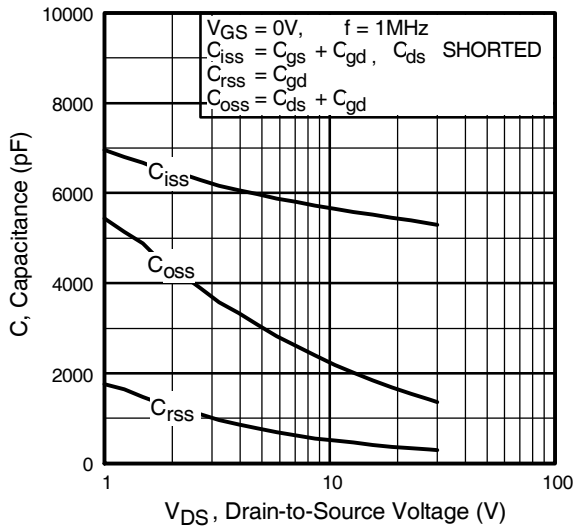


**Fig 3.** Typical Transfer Characteristics

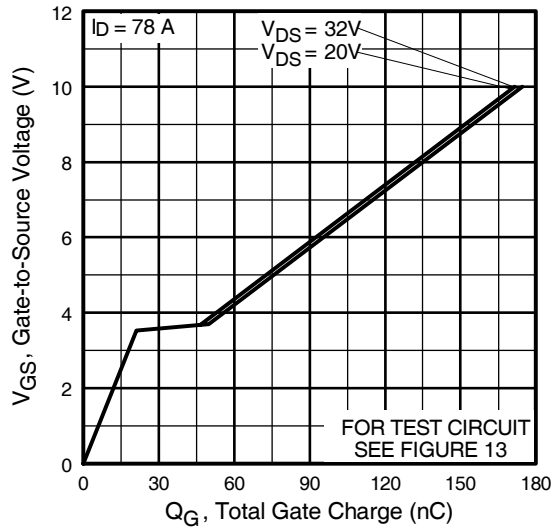


**Fig 4.** Normalized On-Resistance Vs. Temperature

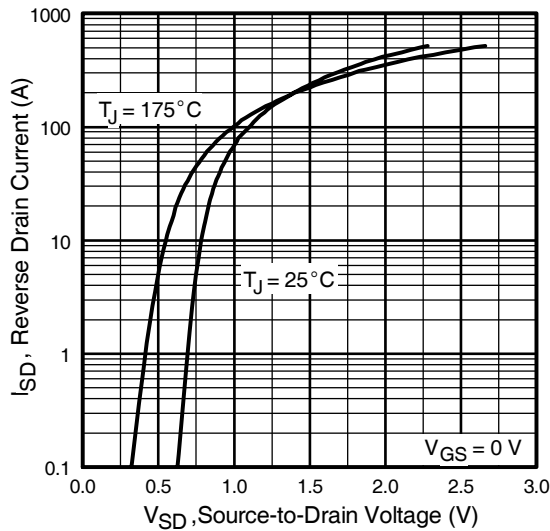
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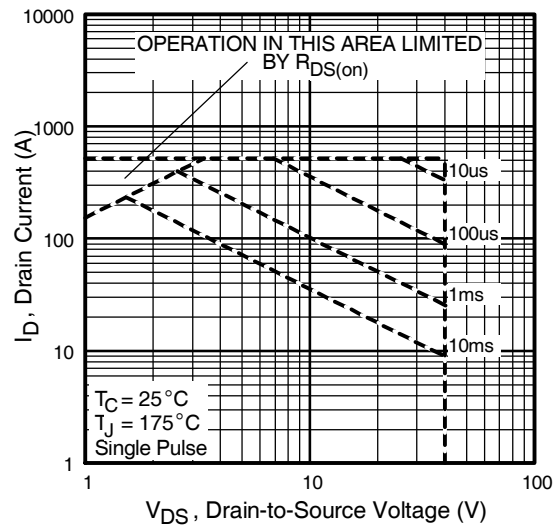
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage



**Fig 8.** Maximum Safe Operating Area

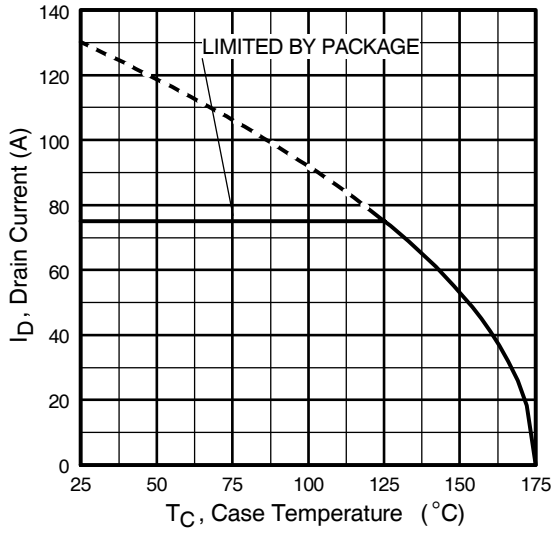


Fig 9. Maximum Drain Current Vs. Case Temperature

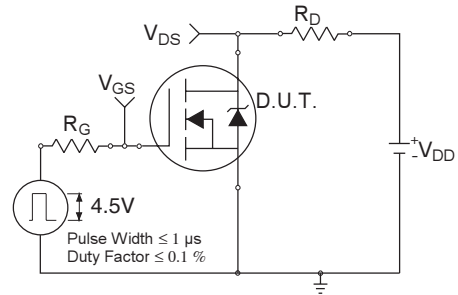


Fig 10a. Switching Time Test Circuit

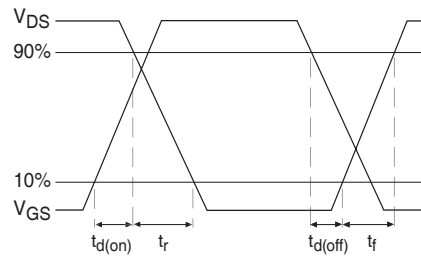


Fig 10b. Switching Time Waveforms

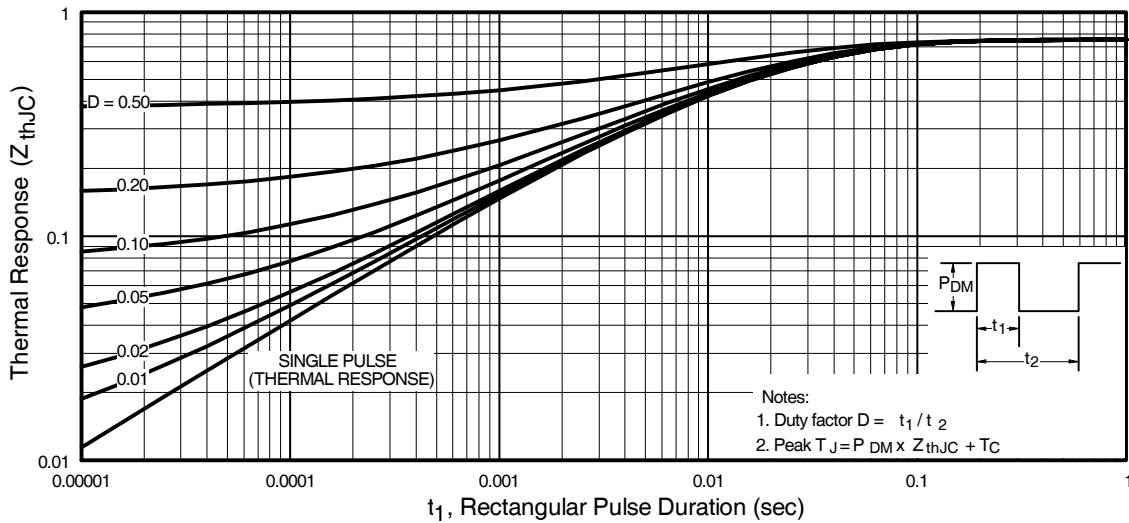
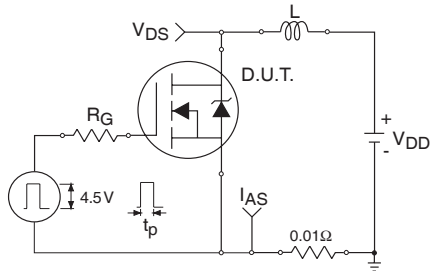


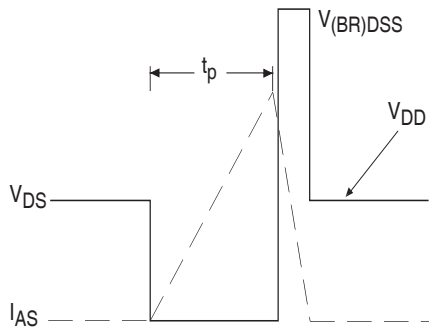
Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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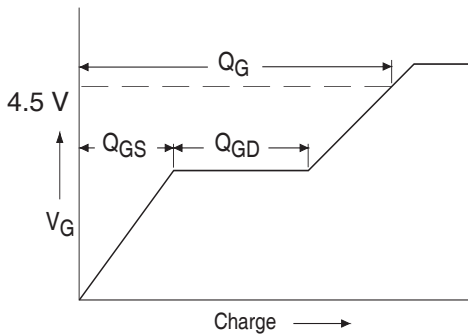
International  
**IRF** Rectifier



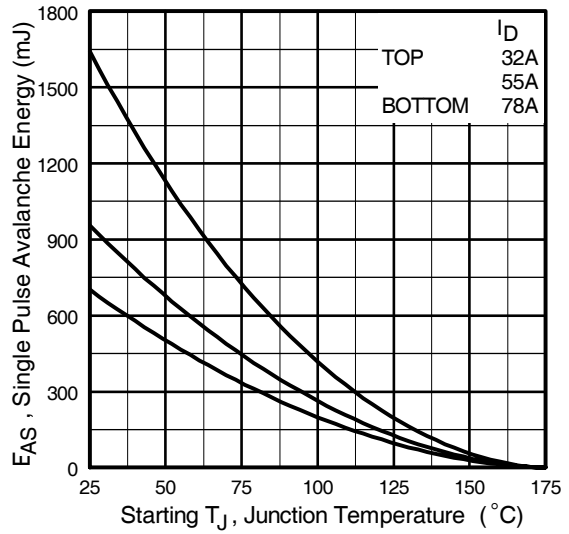
**Fig 12a.** Unclamped Inductive Test Circuit



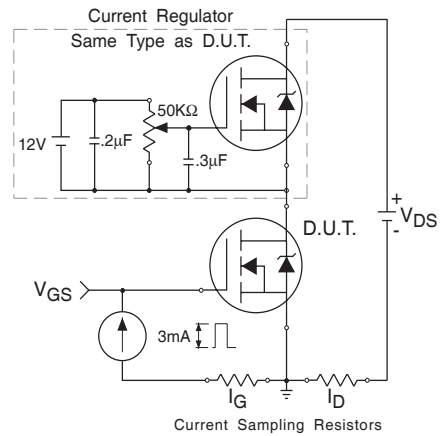
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 13a.** Basic Gate Charge Waveform



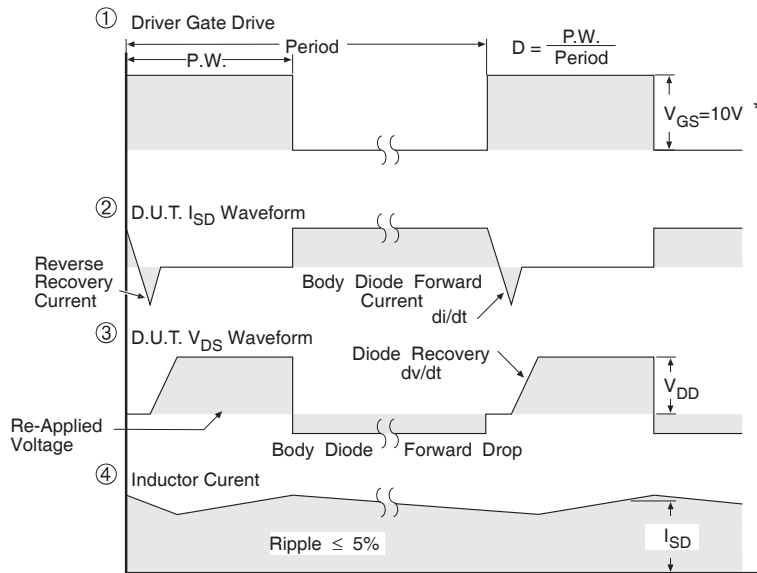
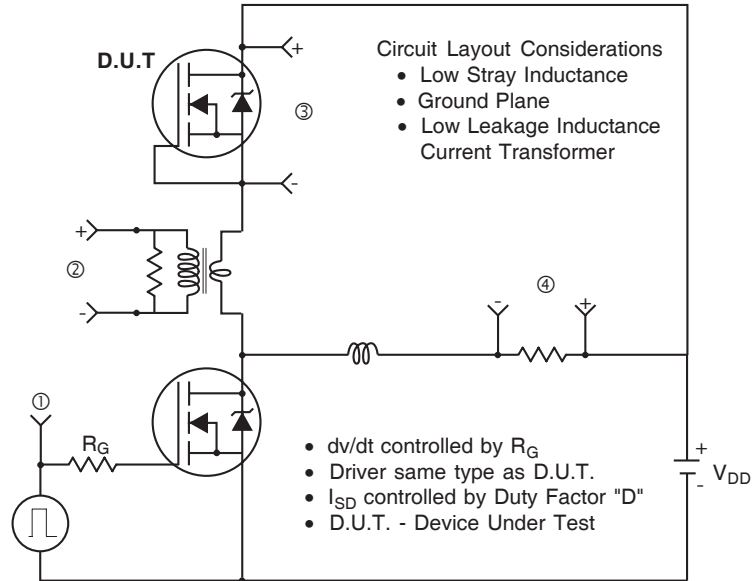
**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 13b.** Gate Charge Test Circuit



**Peak Diode Recovery dv/dt Test Circuit**



\*  $V_{GS} = 5V$  for Logic Level Devices

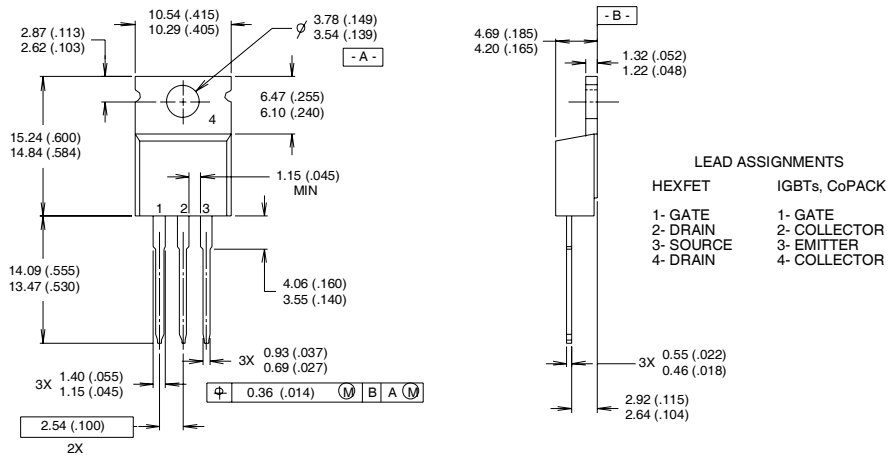
**Fig 14.** For N-Channel HEXFET<sup>®</sup> Power MOSFETs

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## TO-220AB Package Outline

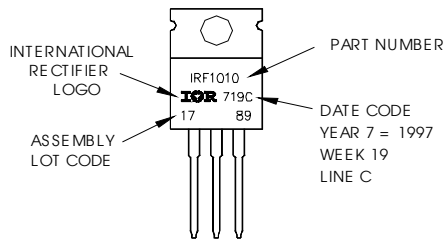
Dimensions are shown in millimeters (inches)



- NOTES:
- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
  - 2 CONTROLLING DIMENSION : INCH
  - 3 OUTLINE CONFORMS TO JEDEC OUTLINE TO-220AB.
  - 4 HEATSINK & LEAD MEASUREMENTS DO NOT INCLUDE BURRS.

## TO-220AB Part Marking Information

EXAMPLE: THIS IS AN IRF1010  
 LOT CODE 1789  
 ASSEMBLED ON WW 19, 1997  
 IN THE ASSEMBLY LINE "C"  
**Note:** "P" in assembly line  
 position indicates "Lead-Free"



Data and specifications subject to change without notice.



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Note: For the most current drawings please refer to the IR website at:  
<http://www.irf.com/package/>

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